

Description

The LM5D200N04 uses advanced technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 40V$ $I_D = 200A$

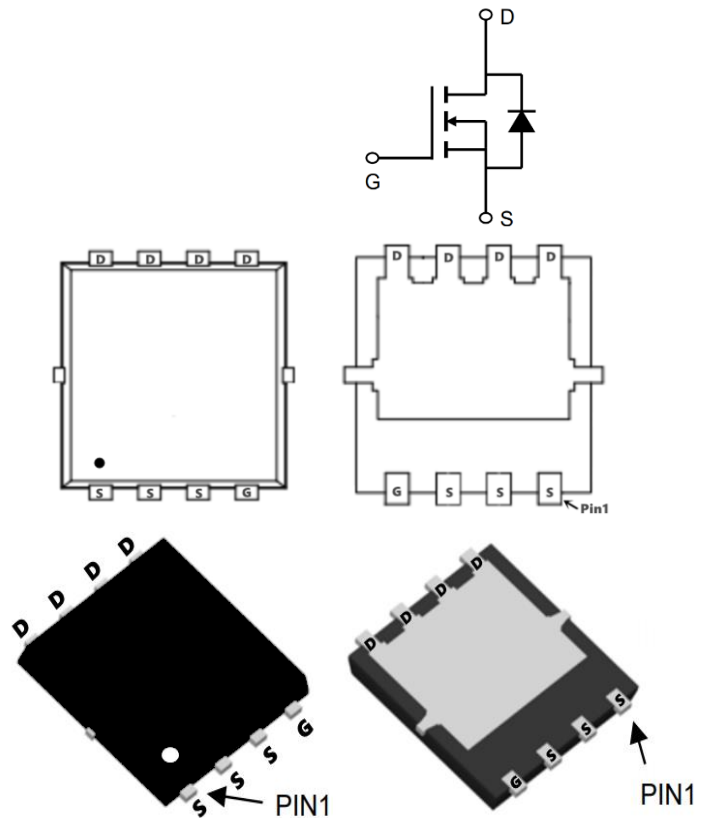
$R_{DS(ON)} < 1.0m\Omega$ @ $V_{GS}=10V$

Application

BMS

BLDC

UPS



Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|------------|----------|---------------------|----------|
| LM5D200N04 | DFN5*6-8 | AP200N04NF XXX YYYY | 5000 |

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

| Symbol | Parameter | Max. | Units |
|------------------------|--------------------------------------------------|------------|--------------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_{D@TC=25^\circ C}$ | Continuous Drain Current, $V_{GS} @ 10V_1$ | 200 | A |
| $I_{D@TC=100^\circ C}$ | Continuous Drain Current, $V_{GS} @ 10V_1$ | 130 | A |
| I_{DM} | Pulsed Drain Current | 800 | A |
| E_{AS} | Single Pulsed Avalanche Energy | 420 | mJ |
| I_{AS} | Avalanche Current | 70 | A |
| $PD@TC=25^\circ C$ | Power Dissipation | 68 | W |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | 25 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 1.4 | $^\circ C/W$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|----------|----------------------------------------------------------|-------------------------------------------------------|------|------|-----------|------------|
| V(BR)DSS | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 40 | 48 | - | V |
| IDSS | Zero Gate Voltage Drain Current | $V_{DS}=40V, V_{GS}=0V,$ | - | - | 1.0 | μA |
| IGSS | Gate to Body Leakage Current | $V_{DS}=0V, V_{GS}= \pm 20V$ | - | - | ± 100 | nA |
| VGS(th) | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.0 | 1.5 | 2.5 | V |
| RDS(on) | Static Drain-Source on-Resistance | $V_{GS}=10V, I_D=30A$ | - | 0.75 | 1.0 | m Ω |
| | | $V_{GS}=4.5V, I_D=20A$ | - | 1.1 | 1.5 | m Ω |
| Ciss | Input Capacitance | $V_{DS}=20V, V_{GS}=0V,$ $f=1.0MHz$ | - | 7400 | - | pF |
| Coss | Output Capacitance | | - | 1930 | - | pF |
| Crss | Reverse Transfer Capacitance | | - | 110 | - | pF |
| Qg | Total Gate Charge | $V_{DS}=20V, I_D=85A,$ $V_{GS}=10V$ | - | 125 | - | nC |
| Qgs | Gate-Source Charge | | - | 18 | - | nC |
| Qgd | Gate-Drain("Miller") Charge | | - | 13 | - | nC |
| td(on) | Turn-on Delay Time | $V_{DD}=20V, I_D=85A,$ $R_G=1.6\Omega, V_{GS}=10V$ | - | 14.1 | - | ns |
| tr | Turn-on Rise Time | | - | 7.9 | - | ns |
| td(off) | Turn-off Delay Time | | - | 56.5 | - | ns |
| tr | Turn-off Fall Time | | - | 9.6 | - | ns |
| IS | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 200 | A |
| ISM | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 800 | A |
| VSD | Drain to Source Diode Forward Voltage | $V_{GS}=0V, I_S=30A$ | - | - | 1.2 | V |
| trr | Body Diode Reverse Recovery Time | $T_J=25^\circ C,$ $I_F=I_S, di/dt=100A/\mu s$ | - | 35 | - | ns |
| Qrr | Body Diode Reverse Recovery Charge | | - | 124 | - | nC |

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、 The EAS data shows Max. rating . The test condition is $V_{DD}=32V, V_{GS}=10V, L=0.1mH, I_{AS}=70A$
- 4、 The power dissipation is limited by $150^\circ C$ junction temperature
- 5、 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Typical Characteristics

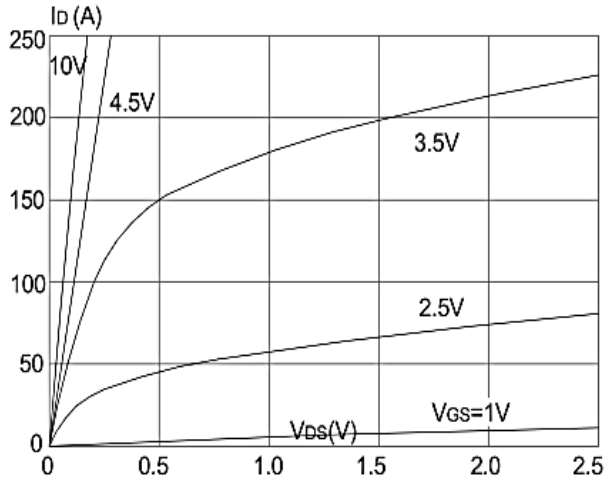


Figure 1: Output Characteristics

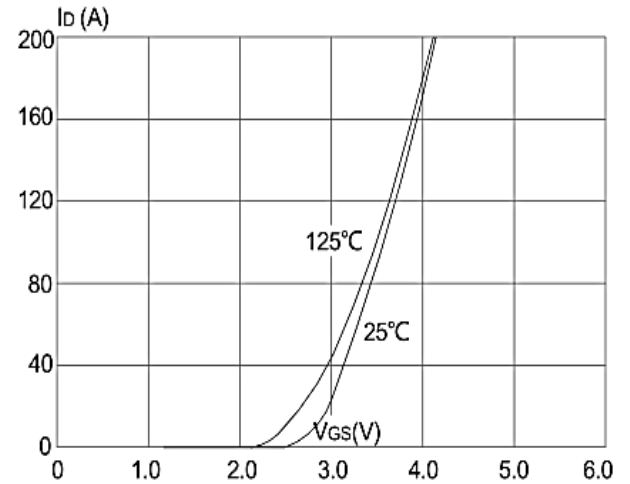


Figure 2: Typical Transfer Characteristics

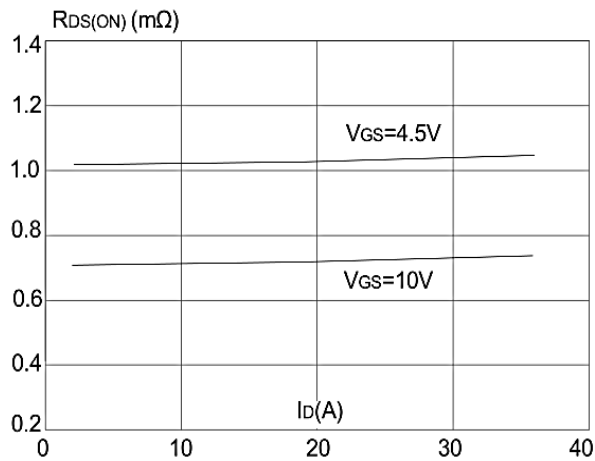


Figure 3: On-resistance vs. Drain Current

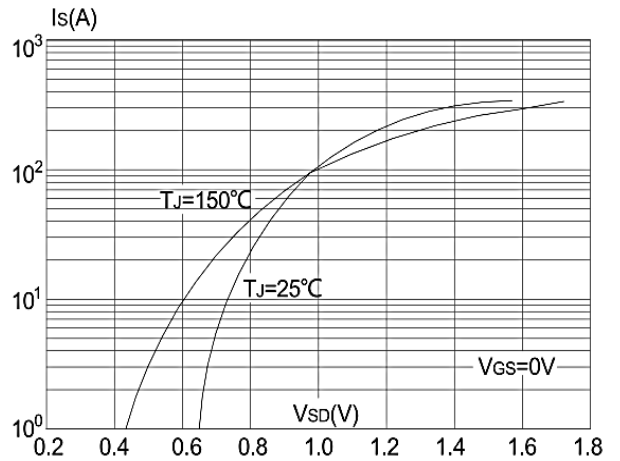


Figure 4: Body Diode Characteristics

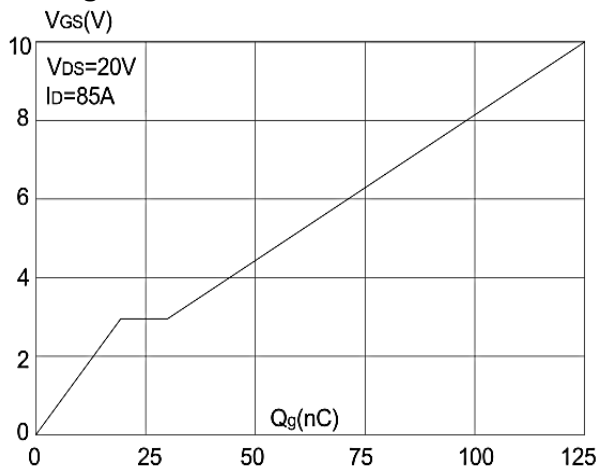


Figure 5: Gate Charge Characteristics

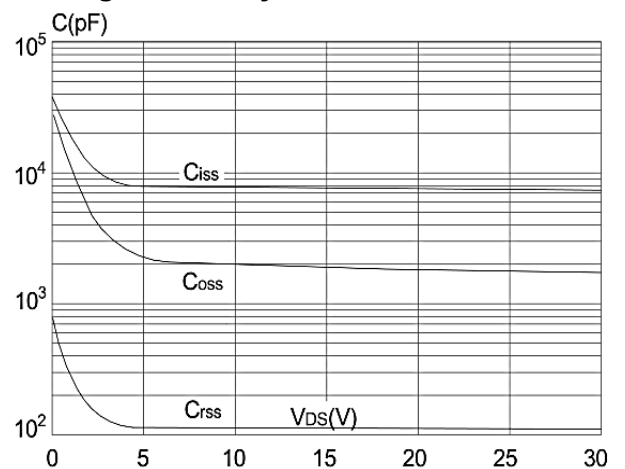


Figure 6: Capacitance Characteristics

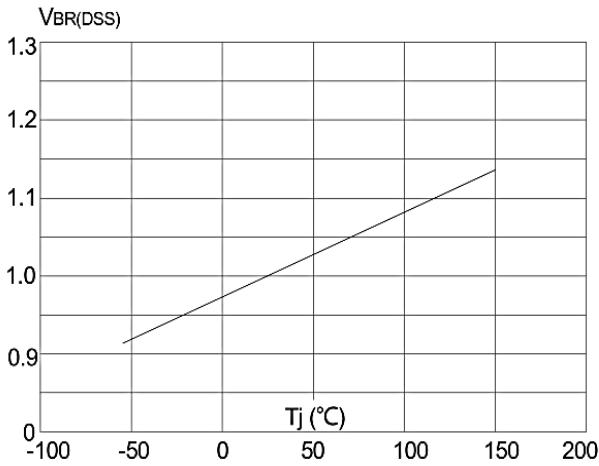


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

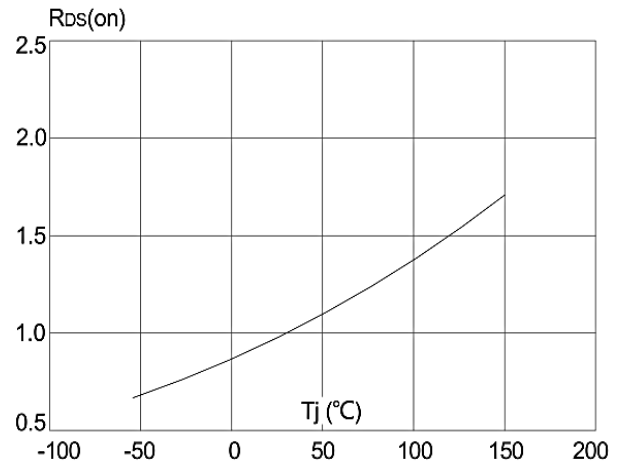


Figure 8: Normalized on Resistance vs. Junction Temperature

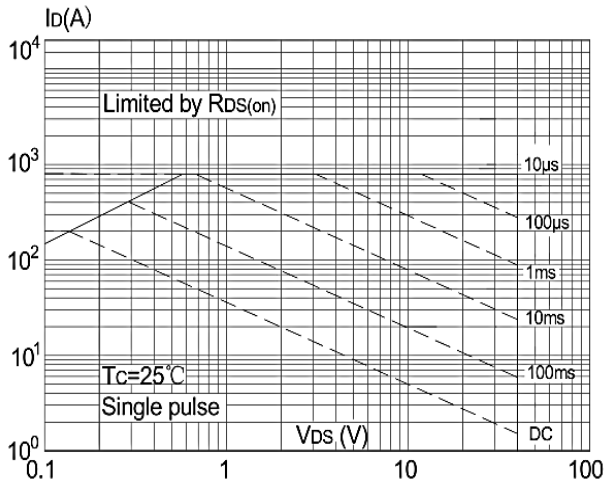


Figure 9: Maximum Safe Operating Area

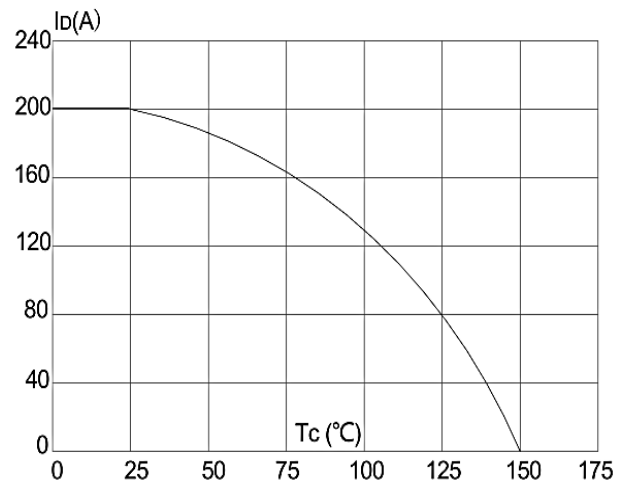


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

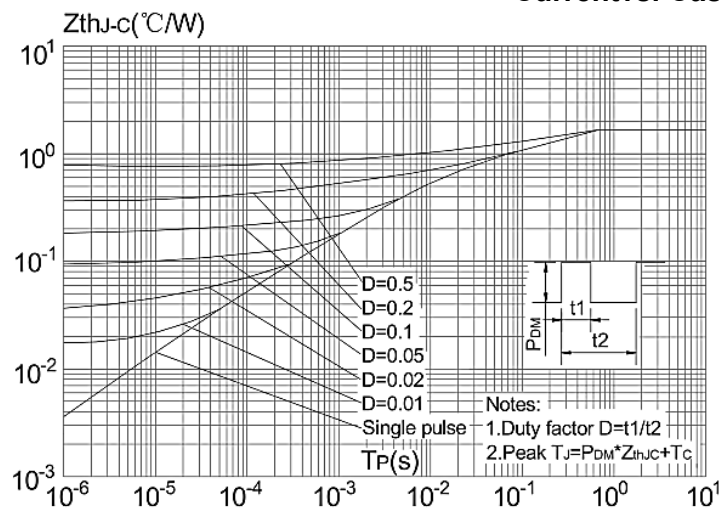
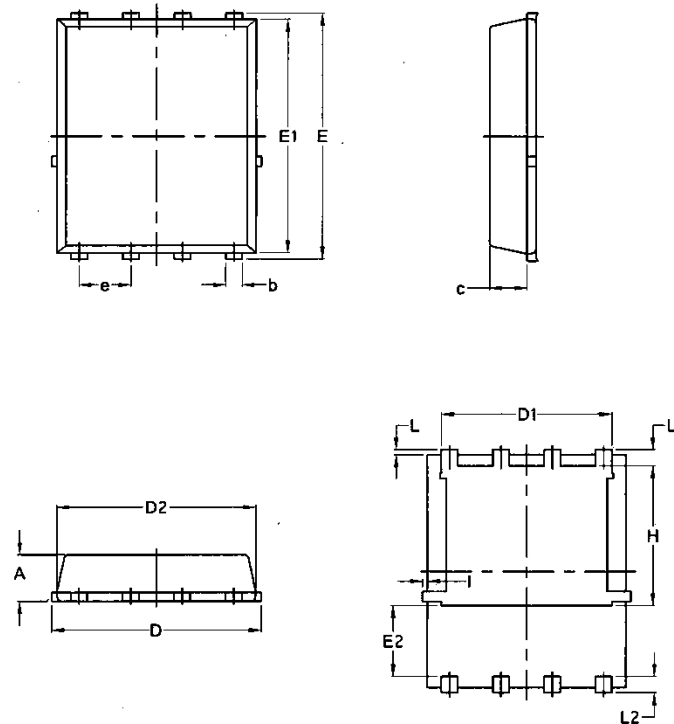


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Cas

Package Mechanical Data-PDFN5*6-8 Single



| Symbol | Common | | | |
|--------|----------|--------|----------|--------|
| | mm | | Inch | |
| | Min | Max | Min | Max |
| A | 1.03 | 1.17 | 0.0406 | 0.0461 |
| b | 0.34 | 0.48 | 0.0134 | 0.0189 |
| c | 0.824 | 0.0970 | 0.0324 | 0.082 |
| D | 4.80 | 5.40 | 0.1890 | 0.2126 |
| D1 | 4.11 | 4.31 | 0.1618 | 0.1697 |
| D2 | 4.80 | 5.00 | 0.1890 | 0.1969 |
| E | 5.95 | 6.15 | 0.2343 | 0.2421 |
| E1 | 5.65 | 5.85 | 0.2224 | 0.2303 |
| E2 | 1.60 | / | 0.0630 | / |
| e | 1.27 BSC | | 0.05 BSC | |
| L | 0.05 | 0.25 | 0.0020 | 0.0098 |
| L1 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| L2 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| H | 3.30 | 3.50 | 0.1299 | 0.1378 |
| I | / | 0.18 | / | 0.0070 |